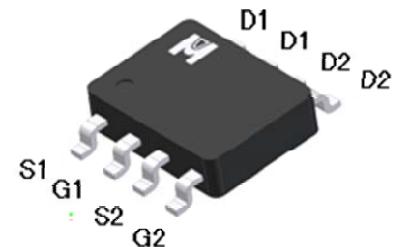
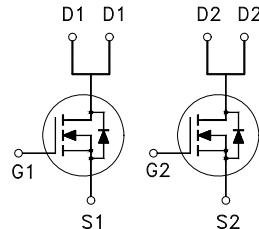


Dual N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	40V
R _{DSON} (MAX.)	22mΩ
I _D	8A



Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNIT
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	8	A
		7	
Pulsed Drain Current ¹	I _{DM}	32	
Power Dissipation	P _D	2	W
		1.3	
Operating Junction & Storage Temperature Range	T _j , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R _{θJC}		25	°C / W
Junction-to-Ambient ³	R _{θJA}		62.5	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

³62.5°C / W when mounted on a 1 in² pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	1.7	3.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 5\text{V}, V_{\text{GS}} = 10\text{V}$	8			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 8\text{A}$		20	22	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 5\text{A}$		30	37	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 8\text{A}$		20		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 20\text{V}, f = 1\text{MHz}$		536		
Output Capacitance	C_{oss}			83		pF
Reverse Transfer Capacitance	C_{rss}			66		
Total Gate Charge ^{1,2}	Q_g	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 8\text{A}$		14.5		
Gate-Source Charge ^{1,2}	Q_{gs}			2.1		nC
Gate-Drain Charge ^{1,2}	Q_{gd}			4.3		
Turn-On Delay Time ^{1,2}	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 20\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GS}} = 6\Omega$		5		
Rise Time ^{1,2}	t_r			10		nS
Turn-Off Delay Time ^{1,2}	$t_{\text{d}(\text{off})}$			15		
Fall Time ^{1,2}	t_f			12		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_S				2.3	
Pulsed Current ³	I_{SM}				9.2	A
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{\text{GS}} = 0\text{V}$			1.3	V

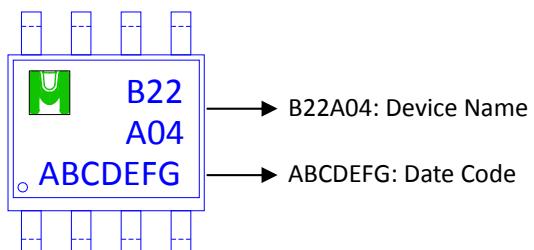
¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

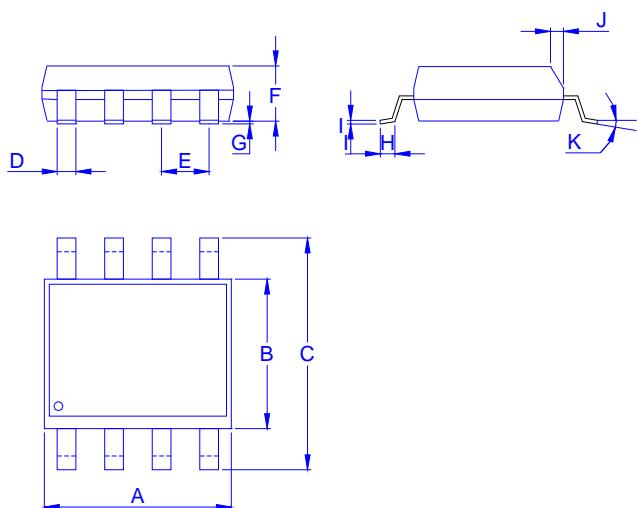
³Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMB22A04G for SOP-8



Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K
Min.	4.70	3.70	5.80	0.33		1.20	0.08	0.40	0.19	0.25	0°
Typ.					1.27						
Max.	5.10	4.10	6.20	0.51		1.62	0.28	0.83	0.26	0.50	8°

TYPICAL CHARACTERISTICS

